

IN THE SPECIFICATION:

Please amend the specification as follows:

Please amend paragraph [0018] as follows:

[0018] Immediately, in step 202, a protecting layer 18 over a surface of the OLED device is formed. The material of the protecting layer 18 can be chosen from a group of metals including platinum (Pt), tungsten (W), etc. In a preferred embodiment of the present invention, the protecting layer 18 can be formed on a cross-section surface of the OLED device by applying a focus ion beam (FIB) technique. The thickness of the protecting layer 18 is preferably about 2 micrometers to 3 micrometers. Upon such a protecting layer 18, various advantages can be obtained. One of those advantages is that the OLED device can be better protected and thus can have satisfied stability to avoid breakdown while proceeding the next milling procedure. Another is that the protecting layer 18 can be used as a mark easy to be observed.

Please amend paragraph [0019] as follows:

[0019] Subsequently, in step 203, milling the OLED device to a thin film with a predetermined thickness is performed. Meanwhile, referring also to Fig.4, a schematic view of the OLED device after performing the milling procedure of FIG.3 is illustrated. In this milling procedure, ~~one side of the OLED device~~ 20, which has one side coated with a protecting layer 18, is firstly chosen to sequentially perform a coarse milling, a intermediate milling, and a fine milling with the focus ion beam (FIB). Then, the other side of the OLED device is used to sequentially perform the same procedure with the same tool (FIB) till that a target thickness of the thin film of the OLED device 20 between 0.2 micrometers to 0.3 micrometers can be obtained. As shown in Fig.4, the holes 2031, 2032, 2033 are made by proceeding the coarse milling, the intermediate milling and the fine milling in turn.

Please amend paragraph [0020] as follows:

[0020] In step 204, the thin film of the OLED device 20 is then removed by cutting both sides of the thin film which may still connect with the original OLED device 20. Preferably, the aforesaid cutting can be executing by performing a focus ion beam (FIB). Finally, an OLED sample for transmission electron microscope (TEM) examination is obtained. While proceeding a cross-section sample examination, the first step is to put the OLED sample on a carbon film. Then, the carbon film with the OLED sample is placed on a mesh to further proceed sample examination by means of TEM.